Application No.: 10/764,149

BSKB Docket No.: 2929-0255P

Honeywell Docket No.: H0006156-1160

Amendment to the specification:

Amend paragraph [0035] as indicated:

[0035] Resin Transfer Molding processing of preforms manufactured in accordance with this invention includes: forming a porous preform in the mold constraint fixture described hereinabove; injecting a molten resin or pitch into the mold; permitting the resin or pitch to cool below its melting point; and removing the impregnated preform form from the mold. The preform(s) can be heated to a temperature between about 290-425°C (554-797°F) either prior to or after being placed in the mold. The mold can be heated to a temperature between about 138-310°C (280-590°F).